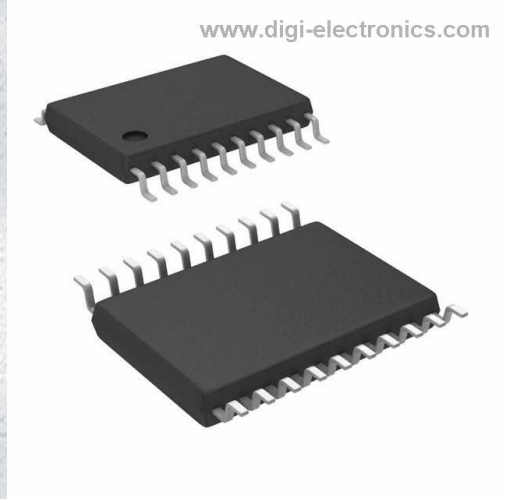
74VHCT245AMTC Datasheet



DiGi Electronics Part Number	74VHCT245AMTC-DG
Manufacturer	onsemi
Manufacturer Product Number	74VHCT245AMTC
Description	IC TXRX NON-INVERT 5.5V 20TSSOP
Detailed Description	Transceiver, Non-Inverting 1 Element 8 Bit per Element 3-State Output 20-TSSOP

https://www.DiGi-Electronics.com

Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
74VHCT245AMTC	onsemi
Series:	Product Status:
74VHCT	Obsolete
Logic Type:	Number of Elements:
Transceiver, Non-Inverting	1
Number of Bits per Element:	Input Type:
8	-
Output Type:	Current - Output High, Low:
3-State	8mA, 8mA
Voltage - Supply:	Operating Temperature:
4.5V ~ 5.5V	-40°C ~ 85°C (TA)
Mounting Type:	Package / Case:
Surface Mount	20-TSSOP (0.173", 4.40mm Width)
Supplier Device Package:	Base Product Number:
20-TSSOP	74VHCT245

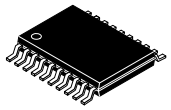
Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8542.39.0001	

DATA SHEET
www.onsemi.com

Octal Buffer/Line Driver with 3-STATE Outputs

74VHCT245A



TSSOP20, 4.4x6.5
CASE 948AQ

General Description

The VHCT245A is an advanced high speed CMOS octal bus transceiver fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The VHCT245A is intended for bidirectional asynchronous communication between data busses. The direction of data transmission is determined by the level of the T/R input. The enable input can be used to disable the device so that the busses are effectively isolated.

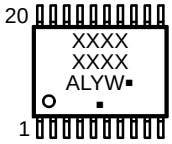
Protection circuits ensure that 0 V to 5.5 V can be applied to the input and output(1) pins without regard to the supply voltage. These circuits prevent device destruction due to mismatched supply and input/output voltages. This device can be used to interface 5 V to 3 V systems and two supply systems such as battery back up.

NOTE:
1. Outputs in OFF−State

Features

- High Speed: t_{PD} = 5.4 ns (Typ) at V_{CC} = 5 V
- Power Down Protection on Inputs and Outputs
- Low Power Dissipation: I_{CC} = 4 μA (Max) @ T_A = 25°C
- Pin and Function Compatible with 74HCT245
- This is a Pb−Free Device

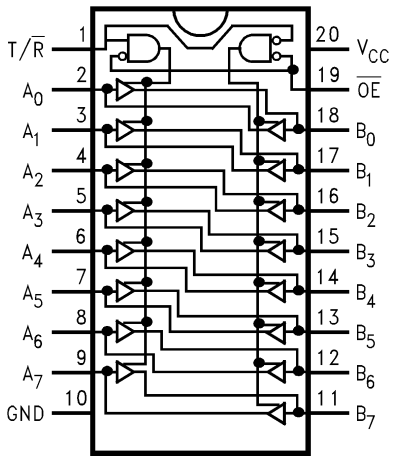
MARKING DIAGRAM



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

CONNECTION DIAGRAM



PIN DESCRIPTION

Pin Names	Description
$\overline{OE}$	Output Enable Input
T/$\overline{R}$	Transmit/Receive Input
A_0–A_7	Side A Inputs or 3−STATE Outputs
B_0–B_7	Side B Inputs or 3−STATE Outputs

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

74VHCT245A

Logic Symbol

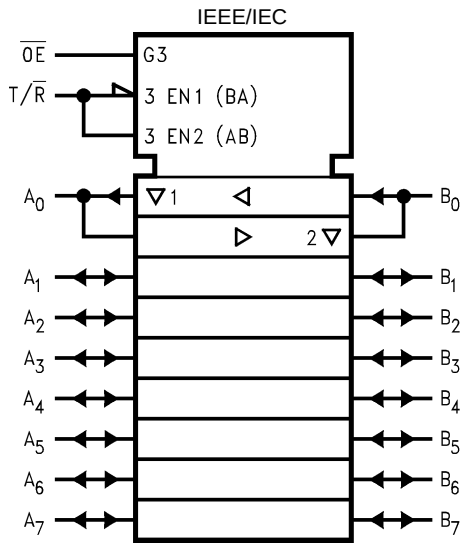


Figure 1. Logic Symbol

TRUTH TABLE

Inputs		Outputs
$\overline{OE}$	T/$\overline{R}$	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	HIGH−Z State

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +6.5	V
V_{IN}	DC Input Voltage		−0.5 to +6.5	V
V_{OUT}	DC Output Voltage	Active Mode (High or Low State)	−0.5 to V_{CC} + 0.5	V
		Tristate Mode (Note 2)	−0.5 to +6.5	
		Power−Off Mode (V_{CC} = 0 V)	−0.5 to +6.5	
I_{IN}	DC Input Current, per Pin		±20	mA
I_{OUT}	DC Output Current, per Pin		±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins		±75	mA
I_{IK}	Input Clamp Current		−20	mA
I_{OK}	Output Clamp Current		−20	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 3)		150	°C/W
P_D	Power Dissipation in Still Air at 25°C		833	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.245 in	
V_{ESD}	ESD Withstand Voltage (Note 4)	Human Body Model	2000	V
		Charged Device Model	N/A	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Applicable to devices with outputs that may be tri−stated.
3. Measured with minimum pad spacing on an FR4 board, using 76 mm−by−114 mm, 2−ounce copper trace no air flow per JESD51−7.
4. HBM tested to EIA / JESD22−A114−A. CDM tested to JESD22−C101−A. JEDEC recommends that ESD qualification to EIA/JESD22−A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage		4.5	5.5	V
V_{IN}	DC Input Voltage (Note 5)		0	5.5	V
V_{OUT}	DC Output Voltage (Note 5)	Active Mode (High or Low State)	0	V_{CC}	V
		Tristate Mode	0	5.5	
		Power−Off Mode (V_{CC} = 0 V)	0	5.5	
T_A	Operating Temperature		−40	+85	°C
t_r, t_f	Input Rise or Fall Rate	V_{CC} = 4.5 V to 5.5 V	0	20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions		V_{CC} (V)	T_A = 25°C			T_A = −40°C to +85°C		Unit
					Min	Typ	Max	Min	Max	
V_{IH}	HIGH Level Input Voltage			4.5	2.0	–	–	2.0	–	V
				5.5	2.0	–	–	2.0	–	
V_{IL}	LOW Level Input Voltage			4.5	–	–	0.8	–	0.8	V
				5.5	–	–	0.8	–	0.8	
V_{OH}	HIGH Level Output Voltage	V_{IN} = V_{IH} or V_{IL}	I_{OH} = –50 μA	4.5	4.40	4.50	–	4.40	–	V
			I_{OH} = –8 mA		3.94	–	–	3.80	–	
V_{OL}	LOW Level Output Voltage	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 50 μA	4.5	–	0.0	0.1	–	0.1	V
			I_{OL} = 8 mA		–	–	0.36	–	0.44	
I_{OZ}	3−STATE Output Off−State Current	V_{IN} = V_{IH} or V_{IL}; V_{OUT} = V_{CC} or GND		5.5	–	–	±0.25	–	±2.5	μA
I_{IN}	Input Leakage Current	V_{IN} = 5.5 V or GND		0–5.5	–	–	±0.1	–	±1.0	μA
I_{CC}	Quiescent Supply Current	V_{IN} = V_{CC} or GND		5.5	–	–	4.0	–	40.0	μA
I_{CCT}	Maximum I_{CC}/Input	V_{IN} = 3.4 V, Other Input = V_{CC} or GND		5.5	–	–	1.35	–	1.50	mA
I_{OFF}	Output Leakage Current (Power Down State)	V_{OUT} = 5.5 V		0.0	–	–	0.5	–	5.0	μA

NOISE CHARACTERISTICS

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = 25°C		Unit
				Typ	Limits	
V_{OLP} (Note 6)	Quiet Output Maximum Dynamic V_{OL}	C_L = 50 pF	5.0	1.2	1.6	V
V_{OLV} (Note 6)	Quiet Output Minimum Dynamic V_{OL}	C_L = 50 pF	5.0	−1.2	−1.6	V
V_{IHD} (Note 6)	Minimum HIGH Level Dynamic Input Voltage	C_L = 50 pF	5.0	–	2.0	V
V_{ILD} (Note 6)	Maximum LOW Level Dynamic Input Voltage	C_L = 50 pF	5.0	–	0.8	V

6. Parameter guaranteed by design.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions		V_{CC} (V)	T_A = 25°C			T_A = −40°C to +85°C		Unit
					Min	Typ	Max	Min	Max	
t_{PLH}, t_{PHL}	Propagation Delay Time		C_L = 15 pF	5.0 ±0.5	−	4.9	7.7	1.0	8.5	ns
			C_L = 50 pF		−	5.4	8.7	1.0	9.5	
t_{PZL}, t_{PZH}	3−STATE Output Enable Time	R_L = 1 kΩ	C_L = 15 pF	5.0 ±0.5	−	9.4	13.8	1.0	15.0	ns
			C_L = 50 pF		−	9.9	14.8	1.0	16.0	
t_{PLZ}, t_{PHZ}	3−STATE Output Disable Time	R_L = 1 kΩ	C_L = 50 pF	5.0 ±0.5	−	10.1	15.4	1.0	16.5	ns
t_{OSLH}, t_{OSHL}	Output to Output Skew	(Note 7)		5.0 ±0.5	−	−	1.0	−	1.0	ns
C_{IN}	Input Capacitance	V_{CC} = Open			−	4	10	−	10	pF
C_{OUT}	Output Capacitance	V_{CC} = 5.0 V			−	13	−	−	−	pF
C_{PD}	Power Dissipation Capacitance	(Note 8)			−	16	−	−	−	pF

7. Parameter guaranteed by design. $t_{OSLH} = |t_{PLH\ max} - t_{PLH\ min}|$; $t_{OSHL} = |t_{PHL\ max} - t_{PHL\ min}|$
8. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC} (Opr.) = $C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$ / 8 (per F/F). The total C_{PD} when n pcs. of the Octal D Flip−Flop operates can be calculated by the equation: C_{PD} (total) = 20 + 12n

ORDERING INFORMATION

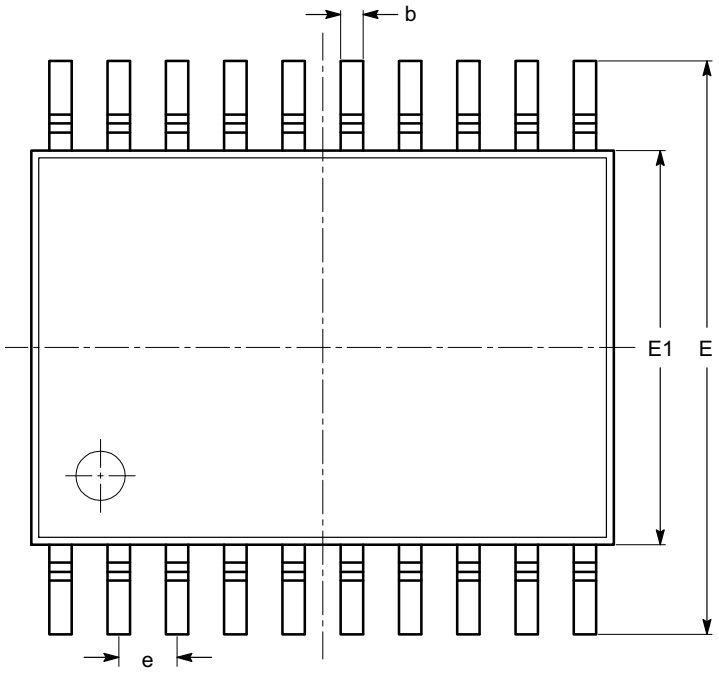
Device	Marking	Package	Shipping†
74VHCT245AMTCX	VHCT 245A	TSSOP20 (Pb−Free)	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

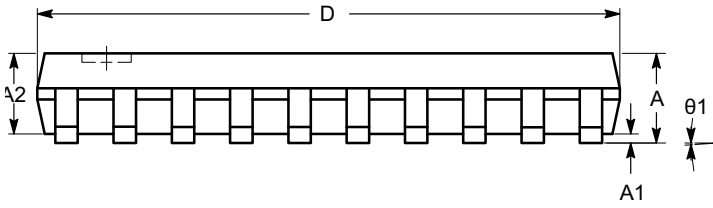
TSSOP20, 4.4x6.5
CASE 948AQ
ISSUE A

DATE 19 MAR 2009

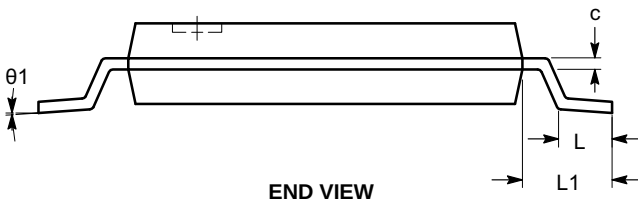


TOP VIEW

SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80		1.05
b	0.19		0.30
c	0.09		0.20
D	6.40	6.50	6.60
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e		0.65 BSC	
L	0.45	0.60	0.75
L1		1.00 REF	
θ	0°		8°



SIDE VIEW



END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-153.

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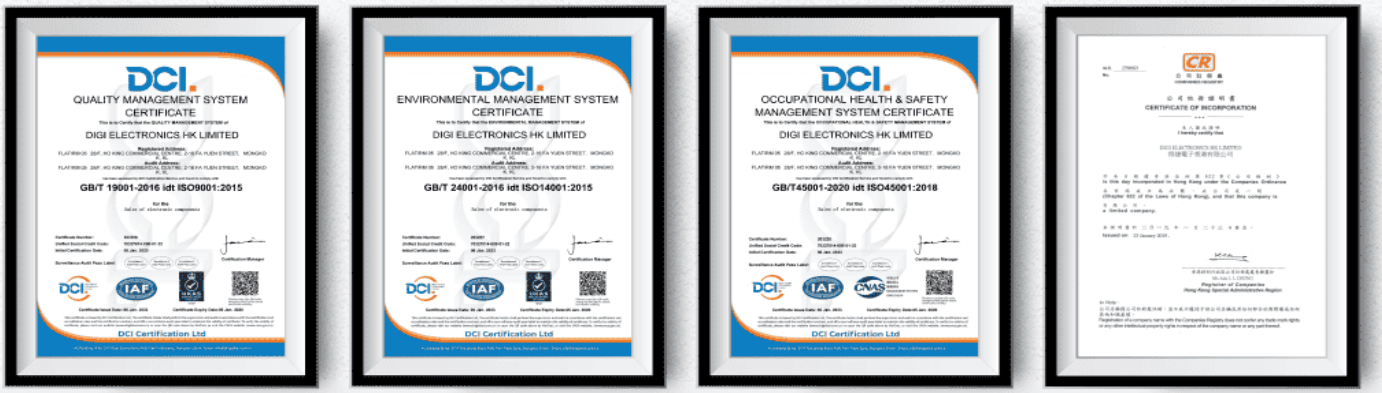

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